

ABSTRACT OF THE DISCLOSURE

A spin coating apparatus for coating photoresist has a spin chuck and a nozzle part. The spin chuck has a mount part on which a wafer is mounted and an extended projection part on which edge-bead is formed. The nozzle part is for depositing photoresist onto the wafer mounted on the mount part of the spin chuck. By using the spin coating apparatus, edge-bead is formed on the extended projection part, and not on the wafer.